

Description

The PSM8PN03R3 uses split gate trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for power management and high efficiency applications at high switching frequencies applications.

MOSFET Product Summary

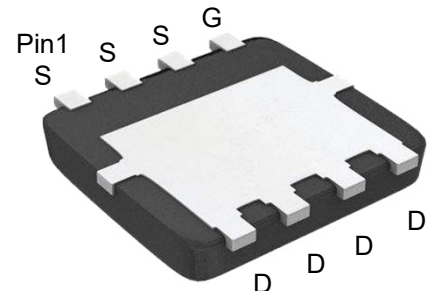
$V_{DS}(V)$	$R_{DS(on)}(m\Omega)(Typ)$	$I_D(A)$
30	1.8@ $V_{GS} = 10V$	108
	2.5@ $V_{GS} = 4.5V$	

Feature

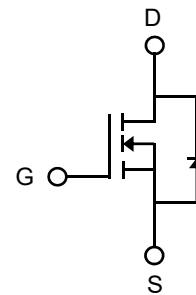
- Low $R_{DS(ON)}$ - Ensures On-State Losses are Minimized
- Excellent $Q_{gd} \times R_{DS(ON)}$ Product(FOM)
- Advanced Technology for DC-DC Converts
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- 100% UIS (Avalanche) Rated
- Lead-Free Finish ; RoHS Compliant
- Halogen and Antimony Free. "Green" Device

Applications

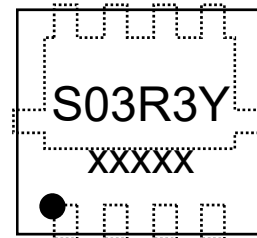
- PWM applications
- Load switch
- Power management
- DC-DC Converters
- Wireless Chargers



**PDFN3333-8L
(Bottom View)**



Circuit Diagram



**Pin1
Marking (Top View)**

Absolute maximum rating@25°C

Rating		Symbol	Value	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Drain Current-Continuous($V_{GS}=10V$) ¹⁾	$T_C=25^\circ C$	I_D	108	A
	$T_C=100^\circ C$		69	
Pulsed Drain Current ²⁾		I_{DM}	434	A
Total Power Dissipation	$T_C=25^\circ C$	P_D	38	W
	$T_C=100^\circ C$		15	
Avalanche Current @ $L=0.1mH$		I_{AS}	45	A
Avalanche Energy ³⁾		E_{AS}	101	mJ
Thermal Resistance , Junction-to-Case ⁵⁾		$R_{\theta JC}$	3.3	$^\circ C/W$
Thermal Resistance Junction-to-Ambient ⁴⁾		$R_{\theta JA}$	56	$^\circ C/W$
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ C$

Electrical characteristics per line@25°C (unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Off Characteristics ⁶⁾						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V,I _D = 10mA	30	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 24V,V _{GS} = 0V	-	-	0.5	mA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V,V _{DS} = 0V	-	-	±100	nA
On Characteristics ⁶⁾						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} ,I _D = 250μA	1.0	1.5	2.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} = 10V,I _D = 20A	-	1.8	2.1	mΩ
		V _{GS} = 4.5V,I _D = 20A	-	2.5	3.2	
Forward Transconductance	g _{fs}	V _{DS} = 5V,I _D = 20A	-	37	-	S
Diode Forward Voltage	V _{SD}	V _{GS} = 0V,I _S = 2A	-	0.5	0.7	V
Dynamic Characteristics ⁷⁾						
Input Capacitance	C _{ISS}	V _{DS} = 15V,V _{GS} = 0V, f = 1.0MHz	-	1437	-	pF
Output Capacitance	C _{OSS}		-	1041	-	
Reverse Transfer Capacitance	C _{rSS}		-	52	-	
Switching Characteristics ⁷⁾						
Turn-on Delay Time	t _{d(on)}	V _{DS} = 15V, V _{GS} = 10V, R _G = 3Ω, I _D = 20A	-	3.0	-	ns
Turn-on Rise Time	t _r		-	11	-	
Turn-Off Delay Time	t _{d(off)}		-	16	-	
Turn-Off Fall Time	t _f		-	12	-	
Total Gate Charge(V _{GS} =10V)	Q _g	V _{DS} =15V, I _D = 20A, V _{GS} =10V,	-	21	-	nC
Gate-Source Charge	Q _{gs}		-	3.8	-	
Gate-Drain Charge	Q _{gd}		-	2.6	-	
Gate Plateau Voltage	V _{plateau}		-	2.7	-	V
Gate Resistance	R _g	V _{GS} =0V,V _{DS} =0V,f=1MHz	-	3.1	-	Ω
Drain-Source Diode Characteristics ⁷⁾						
Body Diode Reverse Recovery Time	t _{rr}	I _F =20A, d _i /d _t =100A/μs	-	31	-	ns
Body Diode Reverse Recovery Charge	Q _{rr}		-	12	-	nC
Diode Forward Current	I _S	-	-	-	60	A

Notes:

1. This current is chip limited, which is calculated based on $R_{\theta JC}$.
2. This current is calculated on single pulse with 10μs Pulse & Duty Cycle = 1%.
3. Defined by design, not subject to production test, EAS condition: $T_J=25^\circ C$, $V_{DD}=15V$, $V_{GS}=10V$, $L=1.0mH$.
4. Device mounted on FR-4 substrate PC board with 2oz copper in 1inch square cooling area.
5. Thermal resistance from junction to the exposed drain pad.
6. Short duration pulse test used to minimize self-heating effect.
7. Defined by design, not subject to production.

Typical Characteristics

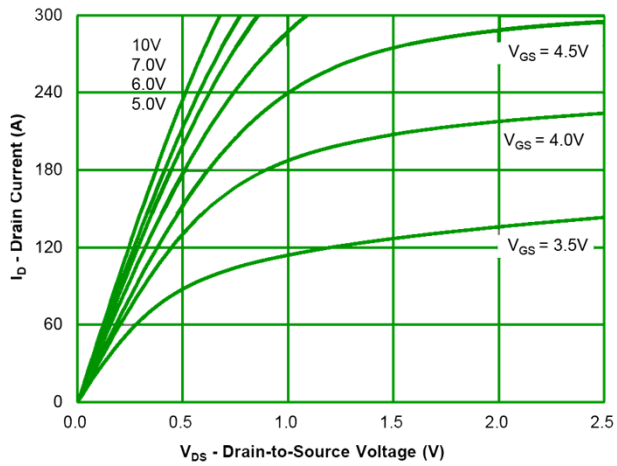


Figure 1: Output Characteristics

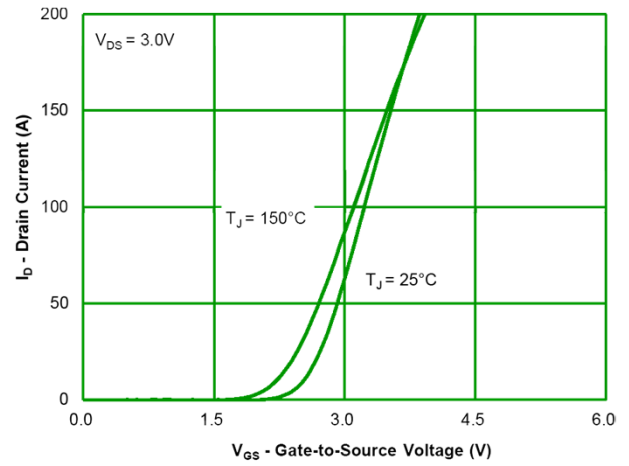


Figure 2: Transfer Characteristics

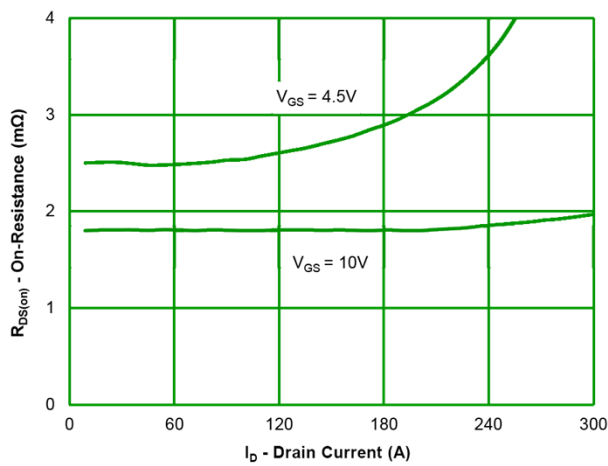


Figure 3: On-Resistance vs. Gate-Source Voltage

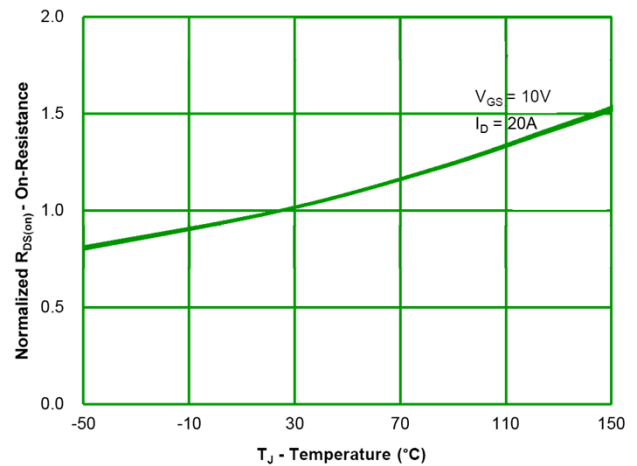


Figure 4: On-Resistance vs. Junction Temperature

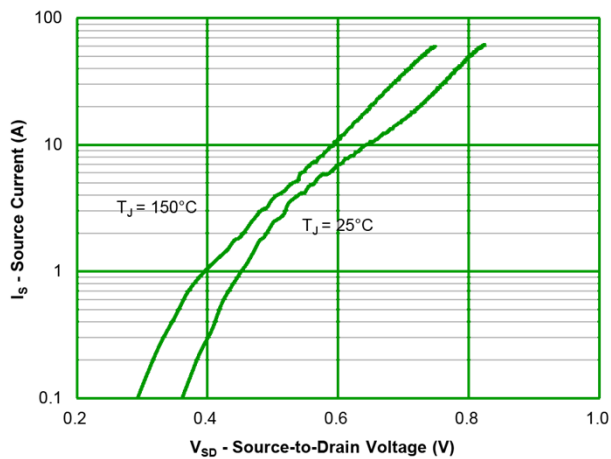


Figure 5: Source-Drain Diode Forward Voltage

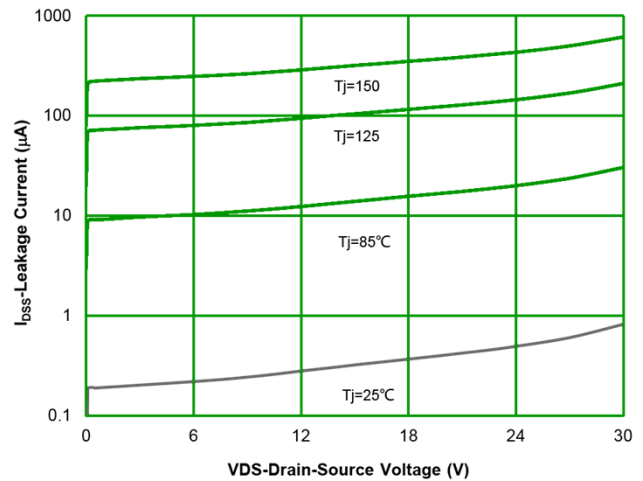


Figure 6: Typical Drain-Source Leakage Current vs Voltage

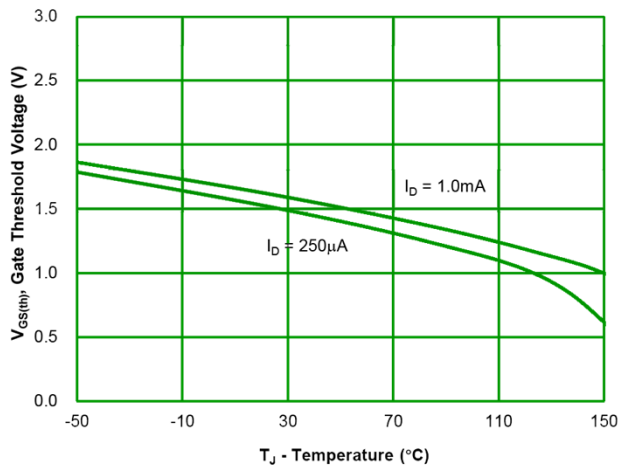


Figure 7: Gate Threshold Variation vs. Junction Temperature

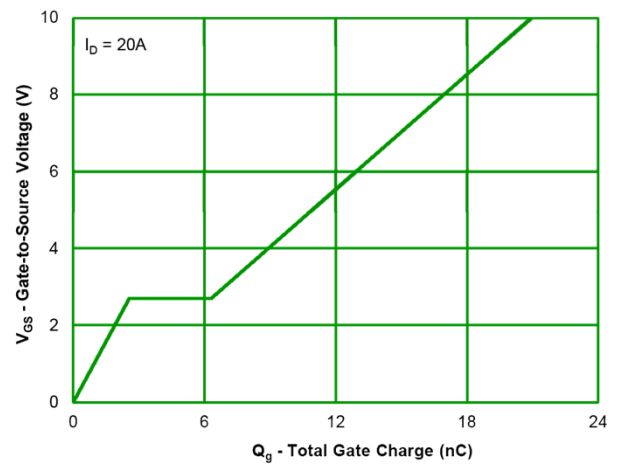


Figure 8: Gate Charge Characteristics

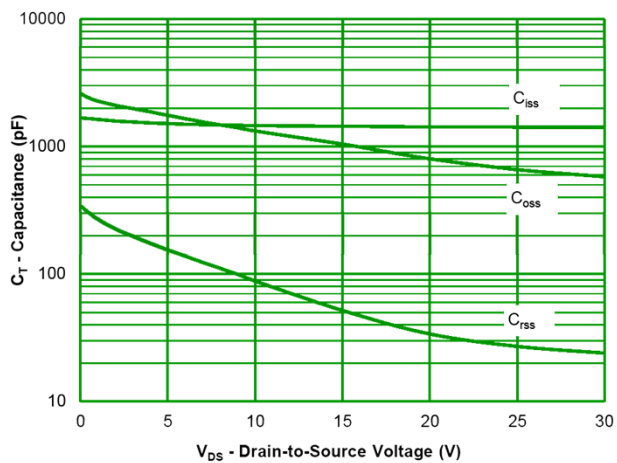


Figure 9: Capacitance Characteristics

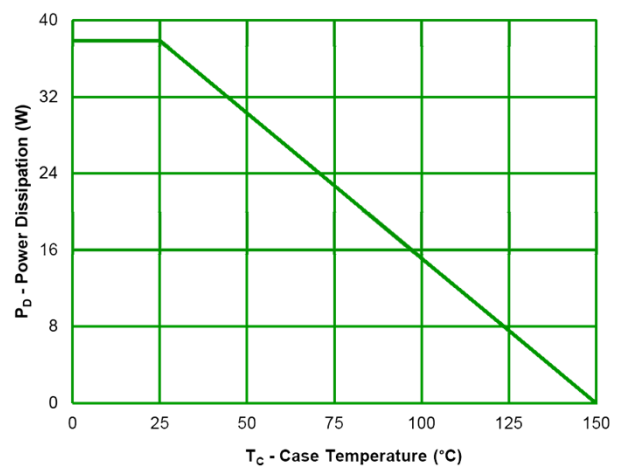


Figure 10: Power Derating

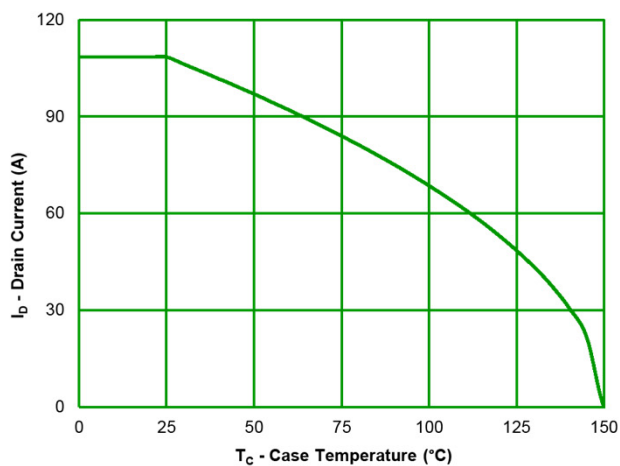


Figure 11: Current Derating

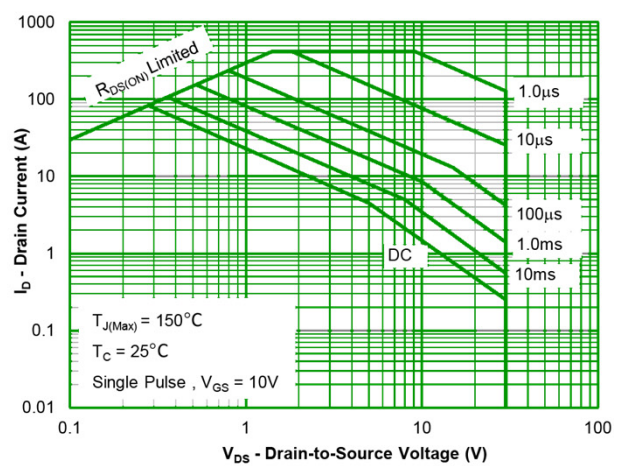


Figure 12: Safe Operating Area

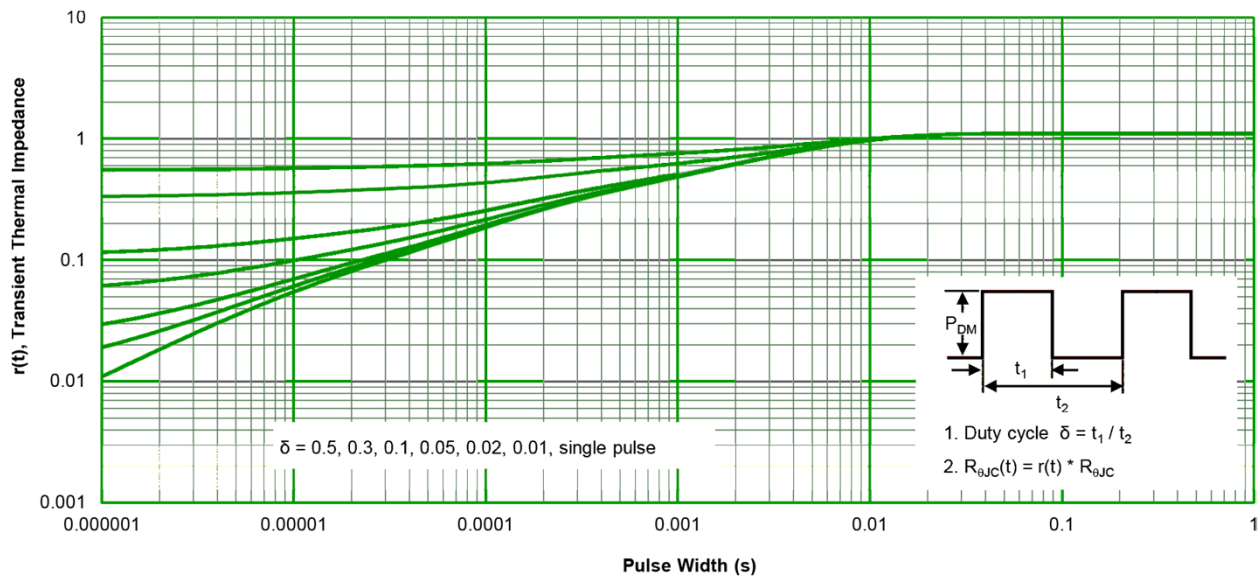
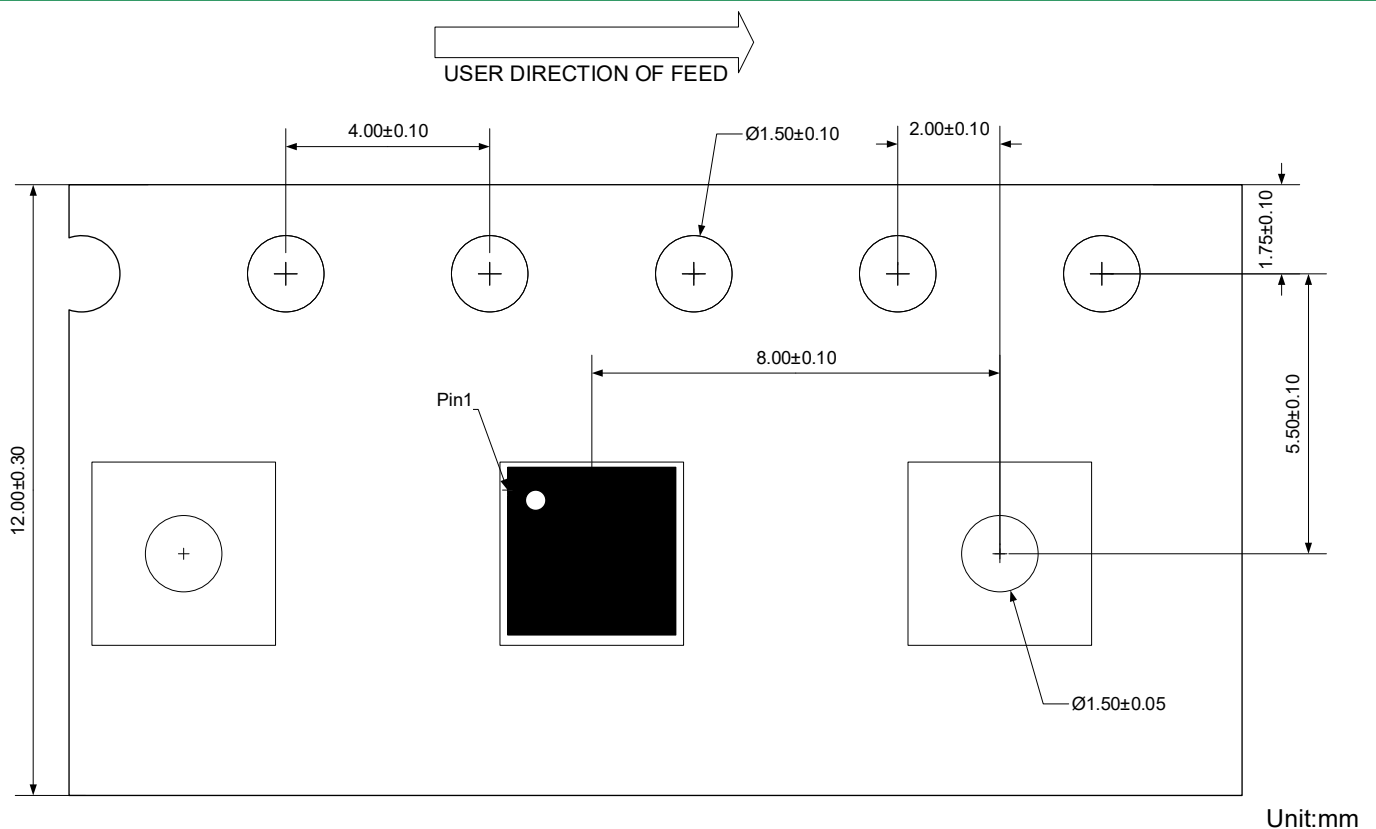


Figure 13: Normalized Maximum Transient Thermal Impedance

Ordering Information

Package	Reel	Shipping
PDFN3333-8L	13"	5000 / Tape & Reel

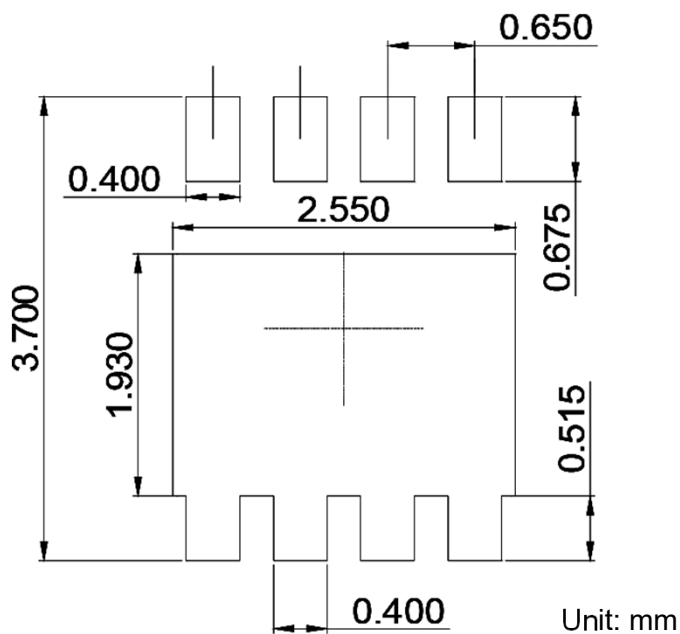
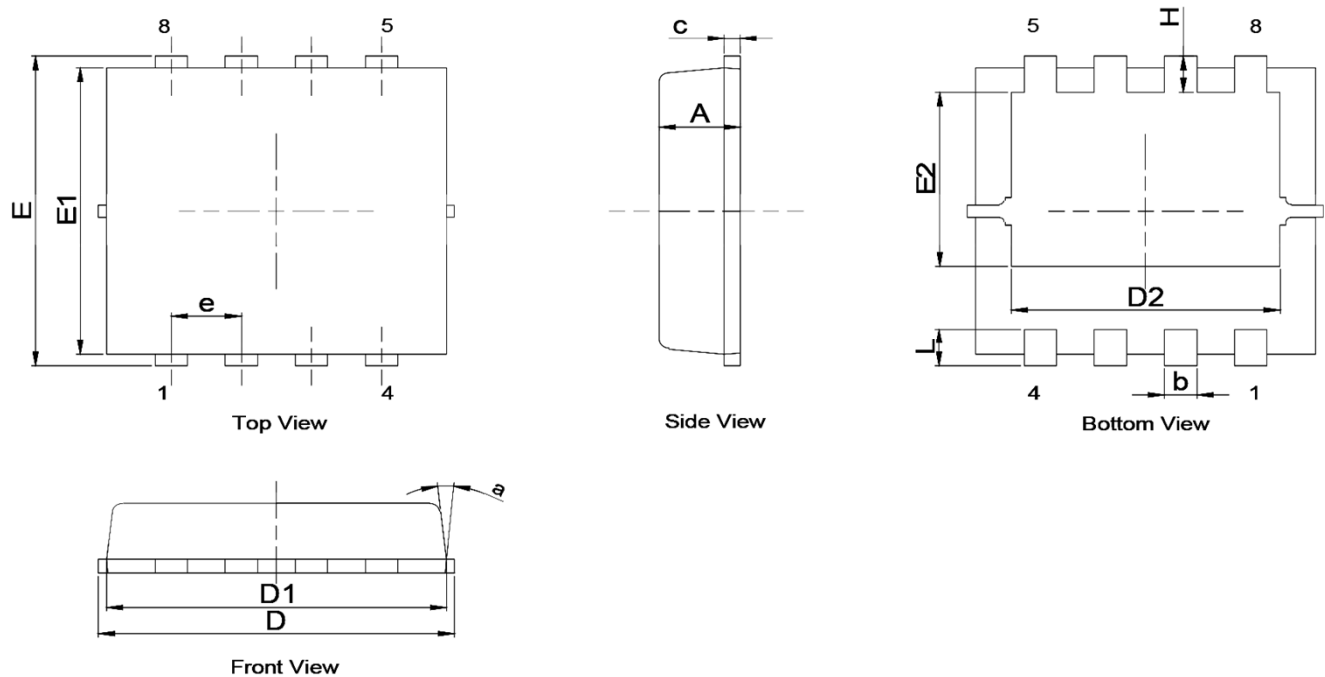
Load With Information



N-Channel MOSFET

PSM8PN03R3


Product Dimension (PDFN3333-8L)



Suggested PCB Layout

Dim	Millimeters		Inches	
	Min	Max	Min	Max
A	0.70	0.90	0.028	0.035
b	0.20	0.40	0.008	0.016
c	0.10	0.25	0.004	0.008
D	3.10	3.40	0.126	0.134
D1	3.00	3.25	0.120	0.128
D2	2.35	2.69	0.093	0.106
E	3.20	3.45	0.126	0.136
E1	2.85	3.20	0.112	0.124
E2	1.48	1.98	0.065	0.075
e	0.65 BSC.		0.026 BSC.	
H	0.25	0.60	0.010	0.024
L	0.25	0.50	0.010	0.020
a	-	15°	-	15°


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